

Title (en)

METHOD FOR MULTI-LAYERED COATING OF SUBSTRATES

Title (de)

VERFAHREN ZUR MEHRSCHICHTIGEN LACKIERUNG VON SUBSTRATEN

Title (fr)

PROCEDE DE LAQUAGE MULTICOUCHE DE SUBSTRATS

Publication

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Application

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Abstract (en)

[origin: US6531188B1] Process for producing a multi-layer lacquer finish, in which a surfacer coating compound is applied to a substrate optionally pre-coated with a priming layer and/or further coating layers, and a top coating comprising a color-imparting and/or special-effect-imparting base lacquer layer and a transparent clear lacquer layer, or a top coating comprising a pigmented one-layer top lacquer, is then applied, in which the surfacer coating compound which is used is one which either contains binders which are curable exclusively by free radical and/or cationic polymerization, wherein the said binders are cured by means of high-energy radiation, or is one which contains binders which are curable by free radical and/or cationic polymerization, wherein the said binders are cured by means of high-energy radiation, and additionally contains chemically cross-linking binders.

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